

L Number	Hits	Search Text	DB	Time stamp
1	604	alignment near5 mark and correction and (wafer or substrate) and exposure and measurement	USPAT; EPO; JPO; DERWENT	2004/09/21 16:26
2	82	(alignment near5 mark and correction and (wafer or substrate) and exposure and measurement) and semiconductor and compar\$4 and exposure adj2 device	USPAT; EPO; JPO; DERWENT	2004/09/21 16:26